

What is claimed is:

Sub 1

1. A mounting socket, comprising:
a socket body having a first side and a second, opposite side, the body having
5 a plurality of vias extending therethrough;
a plurality of conductive terminals within the vias, wherein the terminals
comprise:
an elastically deformable member.
- 10 2. The mounting socket of claim 1, wherein the elastically deformable member
comprises a spring.
- 15 3. The mounting socket of claim 1, wherein the elastically deformable member
comprises a dish spring.
- 20 4. The mounting socket of claim 1, wherein the elastically deformable member
comprises:
a coil; and
a conductive polymer injected within the vias.
- 25 5. The mounting socket of claim 1, and further comprising:
a first adhesive layer affixed to the first side of the body.
6. The mounting socket of claim 5, and further comprising:
25 a polymer tape applied to the first adhesive layer;
a ground and power line circuit laid on the polymer tape; and
a second adhesive layer applied on and protecting the ground and power line
circuit.

Sub 2

7. The mounting socket of claim 5, and further comprising:
a second adhesive layer affixed to the second side of the body.

8. The mounting socket of claim 1, and further comprising:
a push cover attachable to the socket body first and second sides.

Sub a2

2 9. A method of mounting a socket to a board, comprising:
applying an adhesive layer to a board side of the socket;
leveling the adhesive layer to make the adhesive layer substantially coplanar
10 with contact terminals of the socket; and
adhering the socket to the board.

10. The method of claim 9, and further comprising:
applying a second adhesive layer to a package side of the socket opposite the board side of the socket, and
adhering a package to the second adhesive layer.

Sub 63

11. A method of mounting a package to a board using a socket having contact terminals, the method comprising:

20 applying a first adhesive layer to a first, package side of the socket;

 leveling the first adhesive layer to make the adhesive layer substantially coplanar with the contact terminals;

adhering the package to the first adhesive layer;

25 applying a second adhesive layer to a second, board side of the socket;

 leveling the second adhesive layer to make the second adhesive layer substantially coplanar with the contact terminals; and

 adhering the board to the second adhesive layer.

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12. A circuit interconnect, comprising:
a circuit board carrier having a plurality of through holes formed therein; and
a plurality of conductive terminals with lands at each end, each terminal in
one of the through holes, wherein each conductive terminal comprises
an elastically deformable member.

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13. The circuit interconnect of claim 12, and further comprising:
a first adhesive layer affixed to a first side of the circuit board carrier, the first
layer having openings to expose the lands.

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14. The circuit interconnect of claim 13, and further comprising:
a second adhesive layer affixed to a second side of the circuit board carrier,
the second layer having openings to expose the lands, the second side
opposite the first side.

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15. The circuit interconnect of claim 12, wherein the conductive terminals are
conductive rubber.

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16. The circuit interconnect of claim 12, wherein the conductive terminals
comprise a spring.

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17. The circuit interconnect of claim 12, wherein the conductive terminals
comprise:
a compressible coil; and
a conductive polymer injected within the vias.

Sub a4

18. A circuit package, comprising:
a substrate having a plurality of conductive terminals therethrough;

Claim 4
a first adhesive layer affixed to a first side of the substrate; and
a package affixed to the first adhesive layer.

19. The circuit package of claim 18, and further comprising:
5 a second adhesive layer affixed to a second side of the substrate, the second
side opposite the first side.

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20. An integrated circuit, comprising:
a substrate having a plurality of vias therein; and
10 a plurality of elastically deformable terminals, each terminal positioned in a
via.

21. A circuit assembly, comprising:
a substrate having a built-in socket, the socket having a plurality of vias
15 therein;
a plurality of elastically deformable, conductive terminals, each terminal
within a via;
a circuit board having a plurality of mounting areas, the mounting areas in a
plurality of planes which are substantially non-planar with each other;
20 and
wherein each terminal is individually deformable to contact its respective
mounting area at the plane of the mounting area.

25 22. A circuit assembly, comprising:
a microprocessor;
a substrate having a built-in socket having a plurality of vias therein, and a
plurality of conductive, elastically deformable terminals, at least a
portion of the plurality of terminals within a via; and

a motherboard having a plurality of mounting areas thereon, each elastically deformable terminal deformed to contact a mounting area.

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